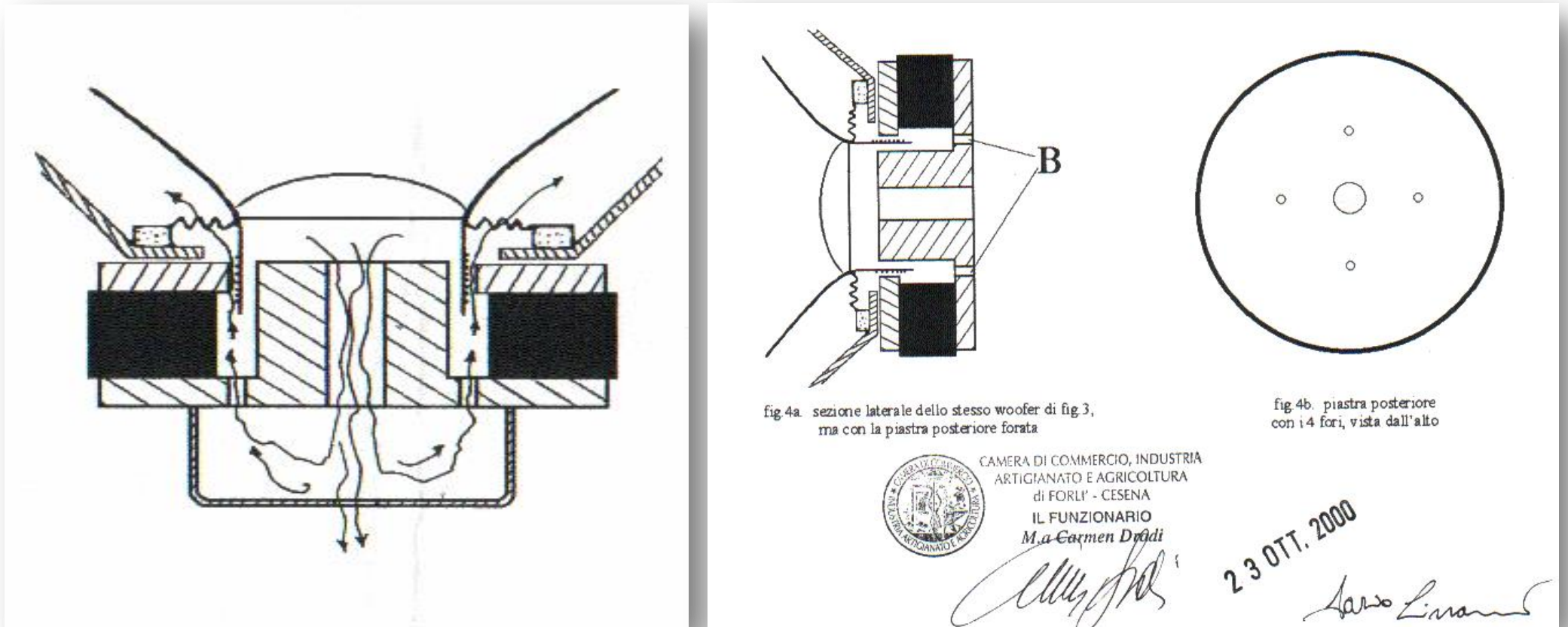
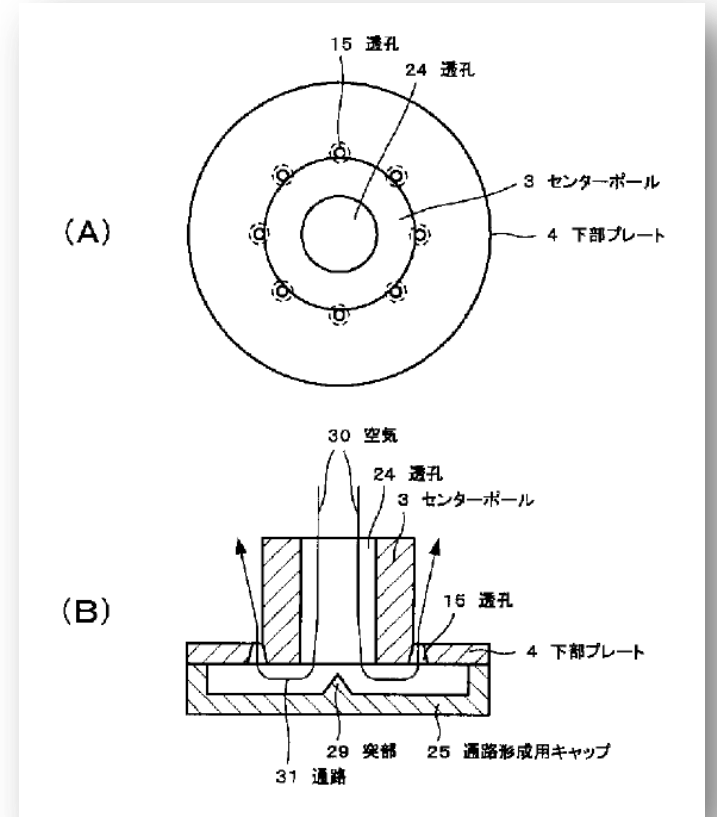
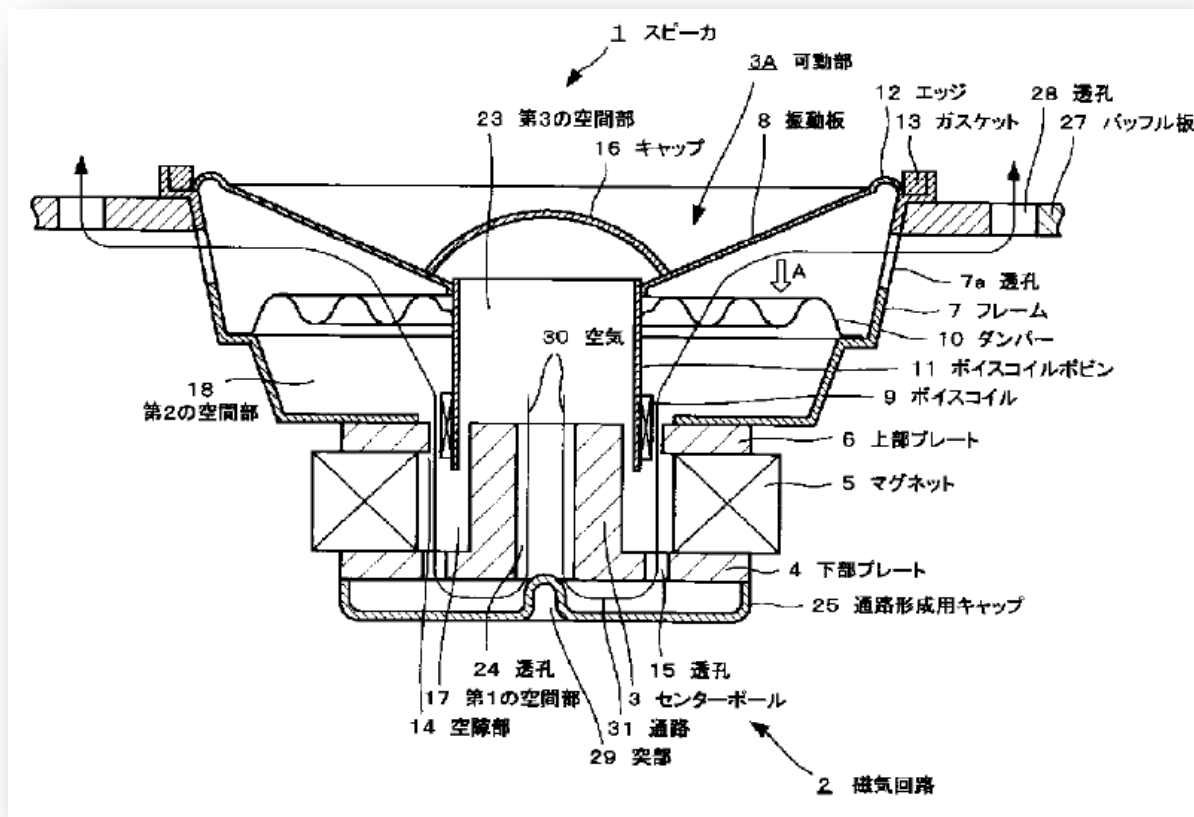


These are two simplified drawings extracted from my first patent (Italian patent N. 257740). Application request: **23 October 2000**.



After more than 3 years:

PATENT ABSTRACTS OF JAPAN vol. 2003, no. 12, **5 December 2003** & JP 2004 186898 A (SONY CORP), **2 July 2004**



The difference between my patent and Sony patent is that in mine there is a hole in the cap to guarantee a lower air compression: a part of air gets out from cap, another part walk across the openings in the back pole plate passing through the gap, cooling voice coil. In loudspeakers with large dimensions and important excursion of mobile parts there is very high compression under the dust cap, air has a high velocity and if this air is forced to pass through small apertures, it creates both a fluid dynamic brake and also great acoustic noise, distortion and in some cases (such as the musical "punch") damages of the dust cap.